

Docket No. 1FT979US/I434.102.101
SEMICONDUCTOR COMPONENT HAVING AT LEAST TWO
CHIPS WHICH ARE INTEGRATED IN A HOUSING AND WITH
WHICH CONTACT IS MADE BY A COMMON CONTACT CHIP

Ralf Otremska
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FIG 1

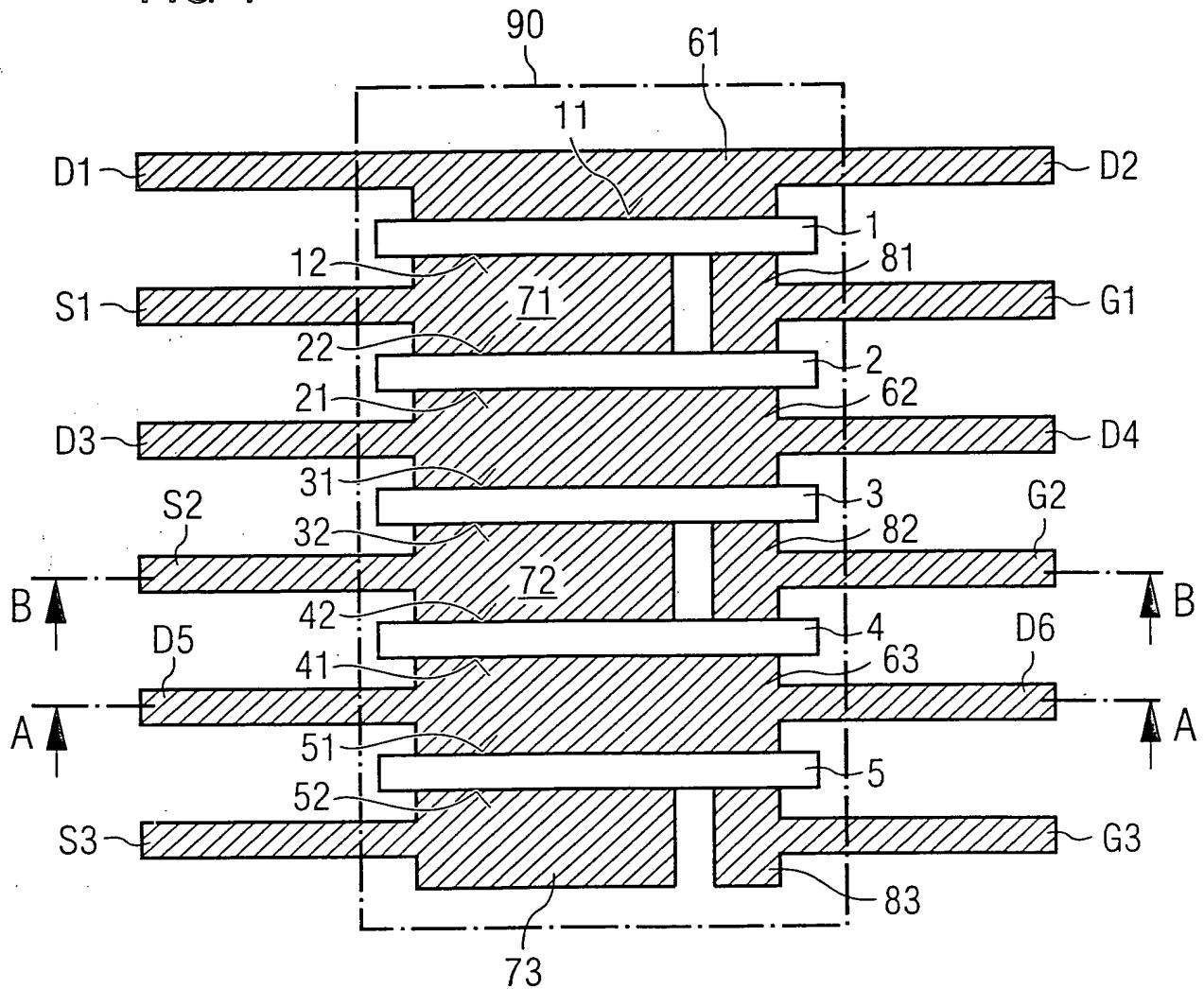


FIG 2 A-A

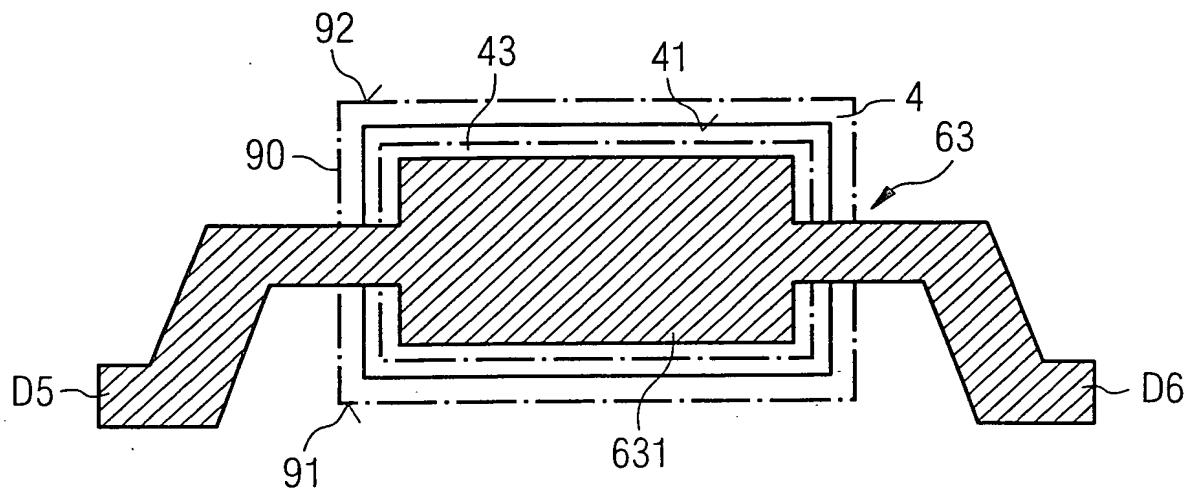


FIG 3 B-B

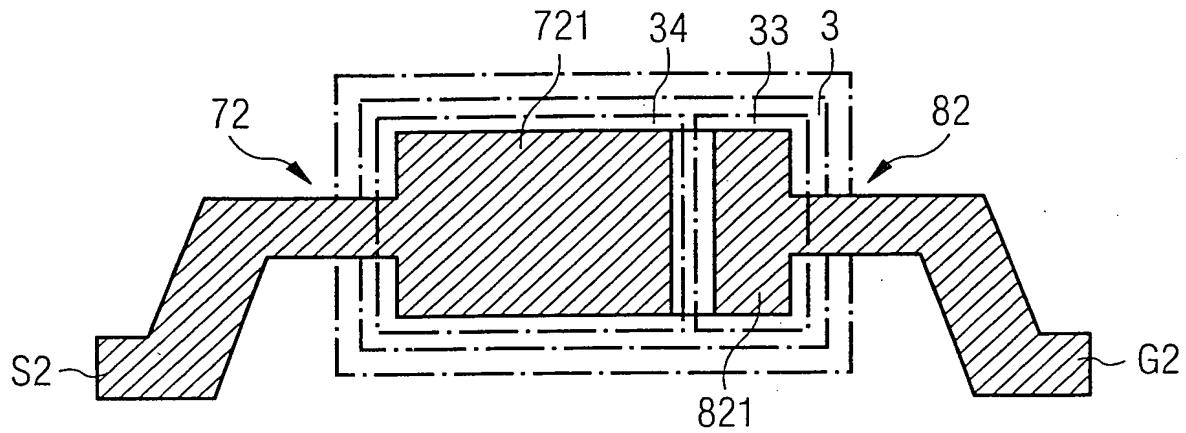


FIG 4

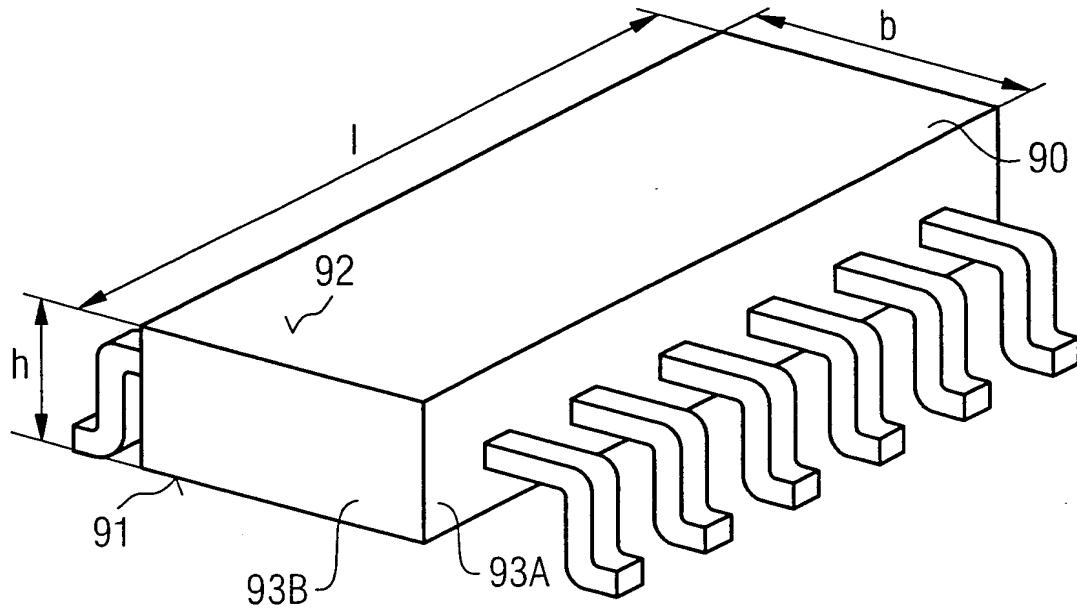
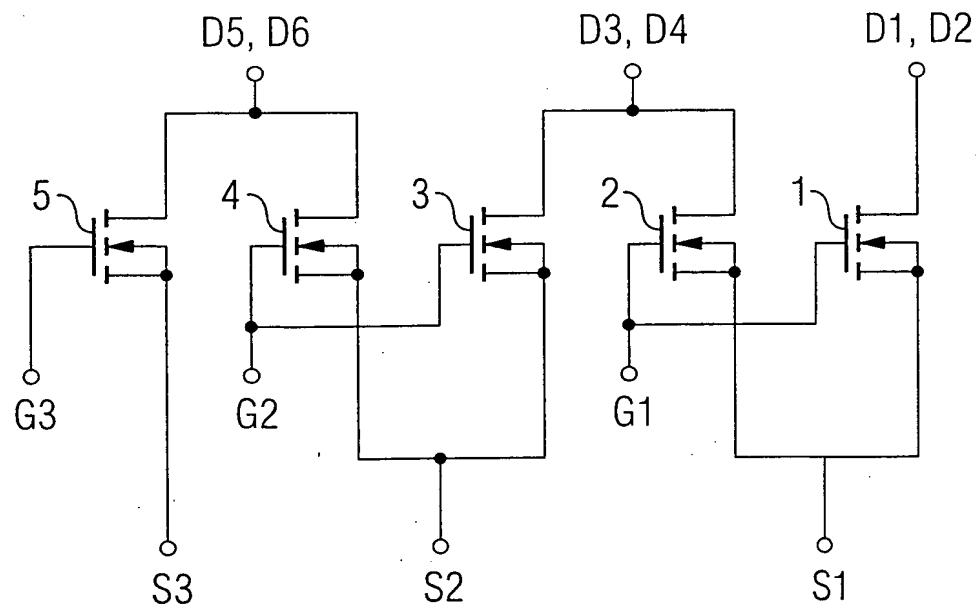


FIG 5



**SEMICONDUCTOR COMPONENT HAVING AT LEAST TWO
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FIG 6

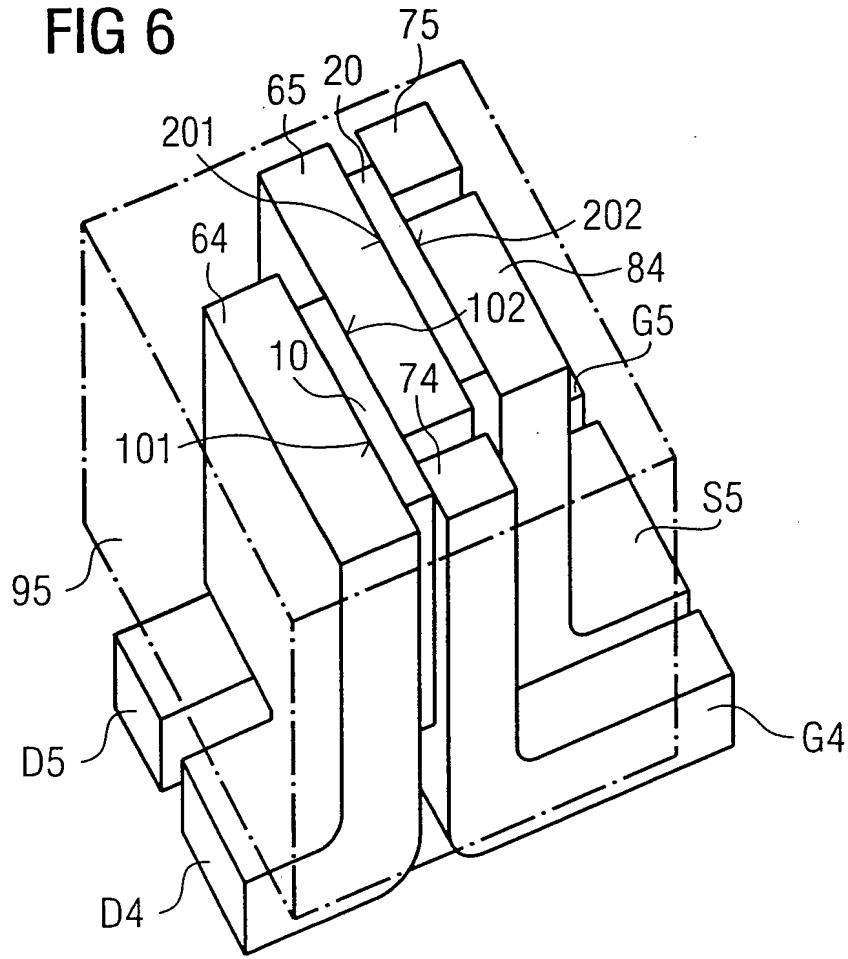


FIG 7

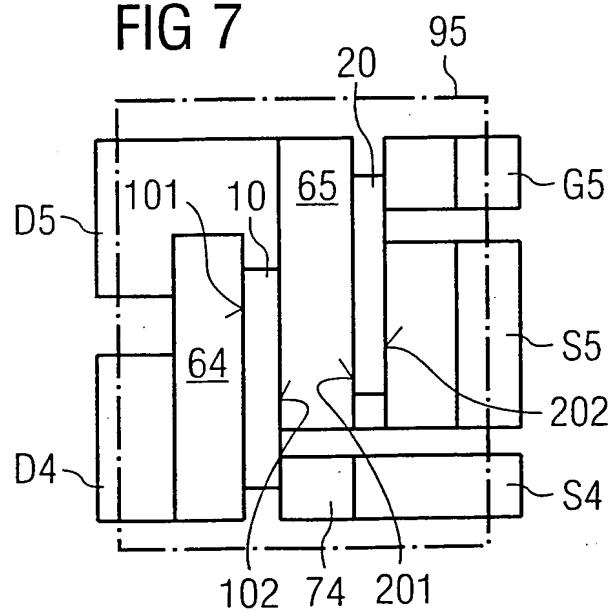


FIG 8

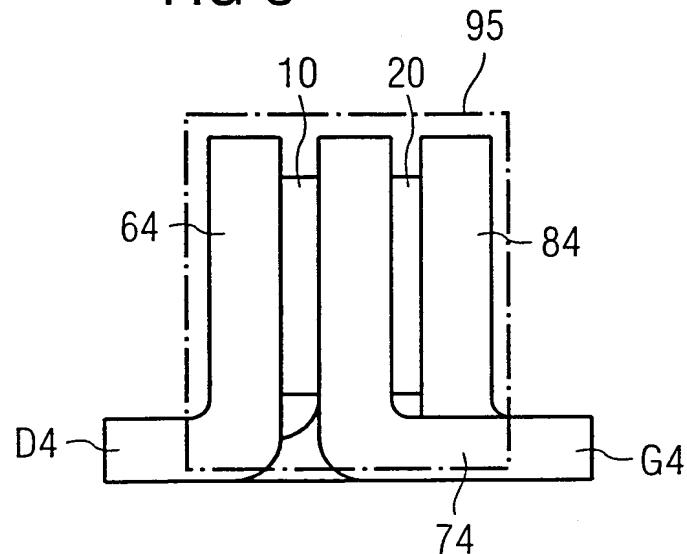


FIG 9

